

Electrical Datasheet GA040TH65-CAU

Silicon Carbide Thyristor

V _{fbm}	=	6500 V
I _{t(avm)}	=	40 A
Q _{rr}	=	1.8 µC

Features

- 6500 V Asymmetric SiC NPNP Thyristor
- 250 °C operating temperature
- Fast turn on characteristics
- Lowest in class Q_{rr}/I_{T(AVM)}

- Applications

 Grid Tied Solar Inverters
- Wind Power Inverters
- HVDC Power Conversion
- Utility Scale Power Conversion
- Trigger Circuits/Ignition Circuits

Maximum Ratings

Parameter	Symbol	Conditions	Values	Unit
Repetitive peak forward voltage	V _{FBM}	T _j = 25 °C	6500	V
Repetitive peak reverse voltage	V _{RBM}	T _j = 25 °C	50	V
Maximum average on-state current	I _{T(AVM)}	T _c ≤ 120 °C	40	А
RMS on-state current	I _{T(RMS)}	T _c ≤ 120 °C	69	А
Operating and storage temperature	T _j , T _{stg}		-55 to 250	°C

Electrical Characteristics

Parameter	Cymele ol	Conditions	Values		11	
	Symbol		min.	typ.	max.	Unit
Maximum peak on state voltage	V	I _κ = -40 A, T _j = 25 °C		-4.30		V
	$V_{_{KA(ON)}}$	I _κ = -40 A, Τ _j = 150 °C		-3.90		
Anode-cathode threshold voltage	V _{KA(TO)}	T _j = 25 °C (150 °C)		-3.1(-2.8)		V
Anode-cathode slope resistance	R _{AK}	T _j = 25 °C (150 °C), I _κ = -40 A		20(21)		mΩ
Leakage current	i	V _{KA} = -6500 V, V _{GA} = 0 V, T _i = 25 °C		15		μA
	L	V _{KA} = -6500 V, V _{GA} = 0 V, T _j = 150 °C		30		
Gate trigger current	І _{дт}	T _j = 25 °C, t _P = 10 μs		-30		mA
Holding current	I _H	T _j = 25 °C		780		mA
Rise time	t _R	I _G = -3 A, V _{KA} = -2500 V		200		ns
Delay time	t _D	I _κ = -40 A, T _j = 25 °C		40		ns
Reverse recovery charge	Q _{rr}			1.8		μC
Recovered charge, 50% chord	Q _{ra}	dl/dt = 270 A/us, I_{K} = -40 A, V_{KA} = 20 V		0.6		μC
Reverse recovery current	I m	dV/dt(re-app) = -500 V/us, T _i = 25 °C		11		Α
Circuit commutated turn-off time	t _a			4.7		μs



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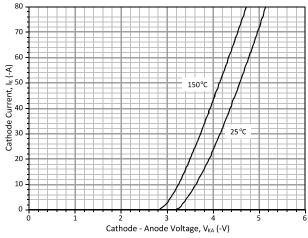
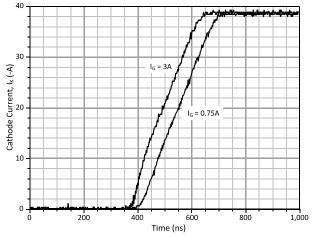
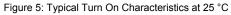


Figure 1: Typical On State Characteristics





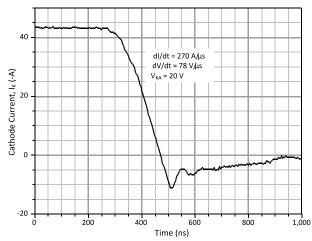


Figure 7: Typical Reverse Recovery Characteristics at 25 °C

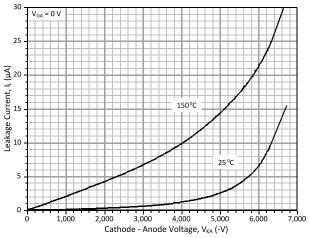


Figure 2: Typical Forward Blocking Characteristics

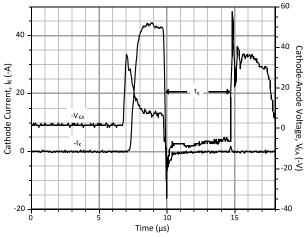


Figure 6: Typical Turn Off Characteristics at 25 °C



Revision History				
Date	Revision	Comments	Supersedes	
2013/11/07	1	First generation release		

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